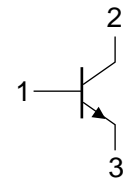
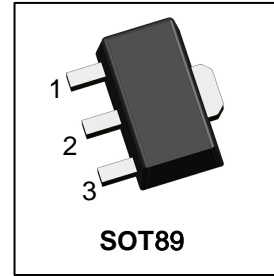


LMBT3904Y3T1G

S-LMBT3904Y3T1G

General Purpose Transistors NPN Silicon



1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.

2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LMBT3904Y3T1G	1AM	1000/Tape&Reel

3. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Collector–Emitter Voltage	V _{CEO}	40	V
Collector–Base Voltage	V _{CBO}	60	V
Emitter–Base Voltage	V _{EB0}	6	V
Collector Current — Continuous	I _C	200	mA

4. THERMAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
Total Device Dissipation, FR-4 Board (Note 1) @ TA = 25°C	PD	550	mW
Derate above 25°C		4.4	mW/°C
Thermal Resistance, Junction–to–Ambient	R _{θJA}	225	°C/W
Junction and Storage temperature	T _J ,T _{stg}	-55~+150	°C

1.PCB Size:30.0mm×25.0mm×1.6mm,FR-4 Board;

5. ELECTRICAL CHARACTERISTICS (Ta= 25°C)
OFF CHARACTERISTICS

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Collector–Emitter Breakdown Voltage (IC = 1.0 mA, IB = 0)	VBR(CEO)	40	-	-	V
Collector–Base Breakdown Voltage (IC = 10 μA, IE = 0)	VBR(CBO)	60	-	-	V
Emitter–Base Breakdown Voltage (IE = 10 μA, IC = 0)	VBR(EBO)	6	-	-	V
Collector Cutoff Current (VCE = 30 V, VEB = 3.0V)	ICEX	-	-	50	nA
Base Cutoff Current (VCE = 30 Vdc, VEB = 3.0Vdc)	IBL	-	-	50	nA

ON CHARACTERISTICS (Note 2.)

DC Current Gain (IC = 0.1 mA, VCE = 1.0 V)	HFE	40	-	-	
(IC = 1.0 mA, VCE = 1.0 V)		70	-	-	
(IC = 10 mA, VCE = 1.0 V)		100	-	300	
(IC = 50 mA, VCE = 1.0 V)		60	-	-	
(IC = 100 mA, VCE = 1.0 V)		30	-	-	
Collector–Emitter Saturation Voltage (IC = 10 mA, IB = 1.0 mA)	VCE(sat)	-	-	0.2	V
(IC = 50 mA, IB = 5.0 mA)		-	-	0.3	
Base–Emitter Saturation Voltage (IC = 10 mA, IB = 1.0 mA)	VBE(sat)	-	-	0.85	V
(IC = 50 mA, IB = 5.0 mA)		-	-	0.95	

SMALL–SIGNAL CHARACTERISTICS

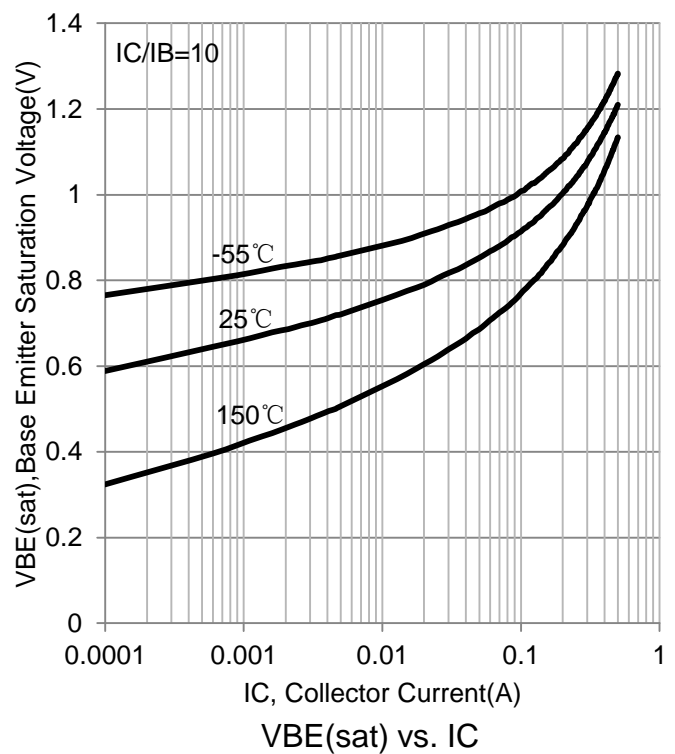
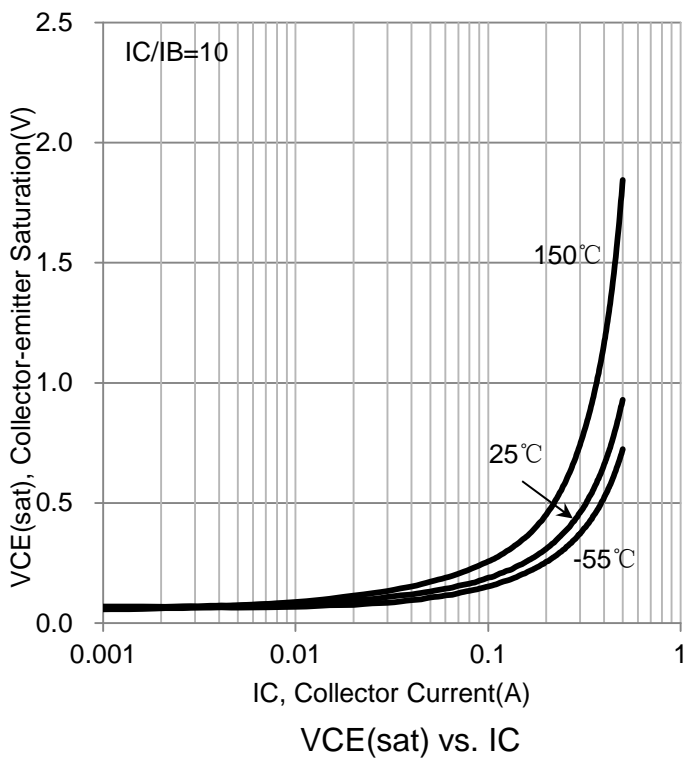
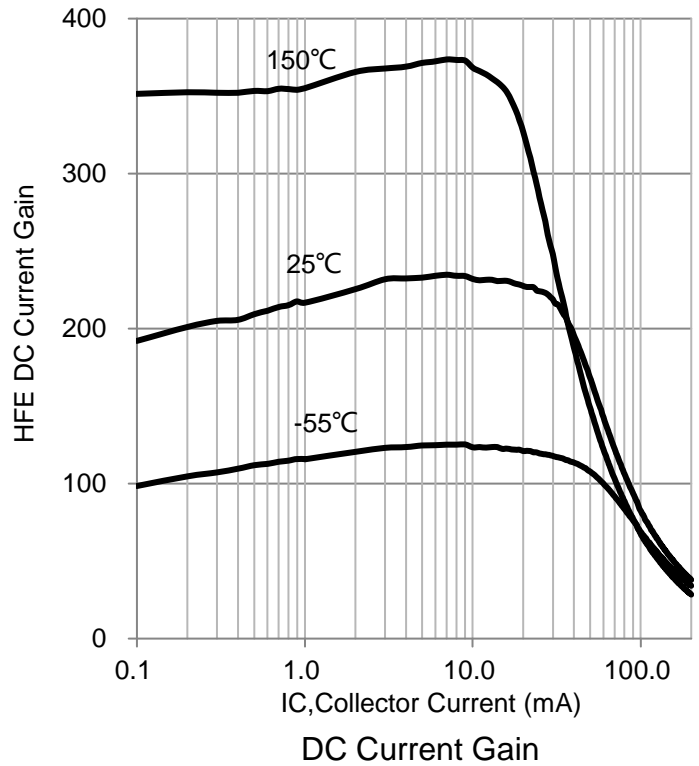
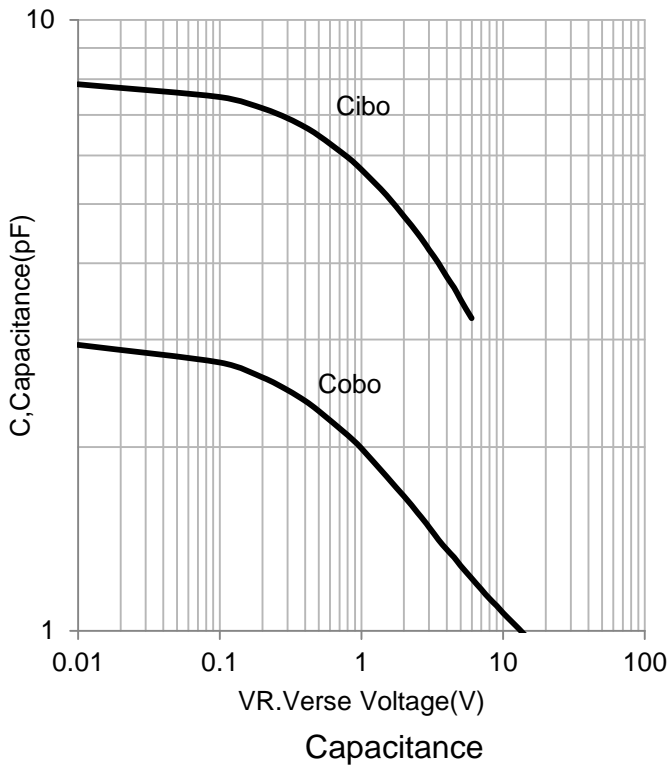
Current–Gain — Bandwidth Product (IC = 10mA, VCE= 20V, f = 100MHz)	fT	-	300	-	MHz
Output Capacitance (VCB = 5.0 V, IE = 0, f = 1.0 MHz)	Cobo	-	-	4	pF
Input Capacitance (VEB = 0.5 V, IC = 0, f = 1.0 MHz)	Cibo	-	-	8	pF

SWITCHING CHARACTERISTICS

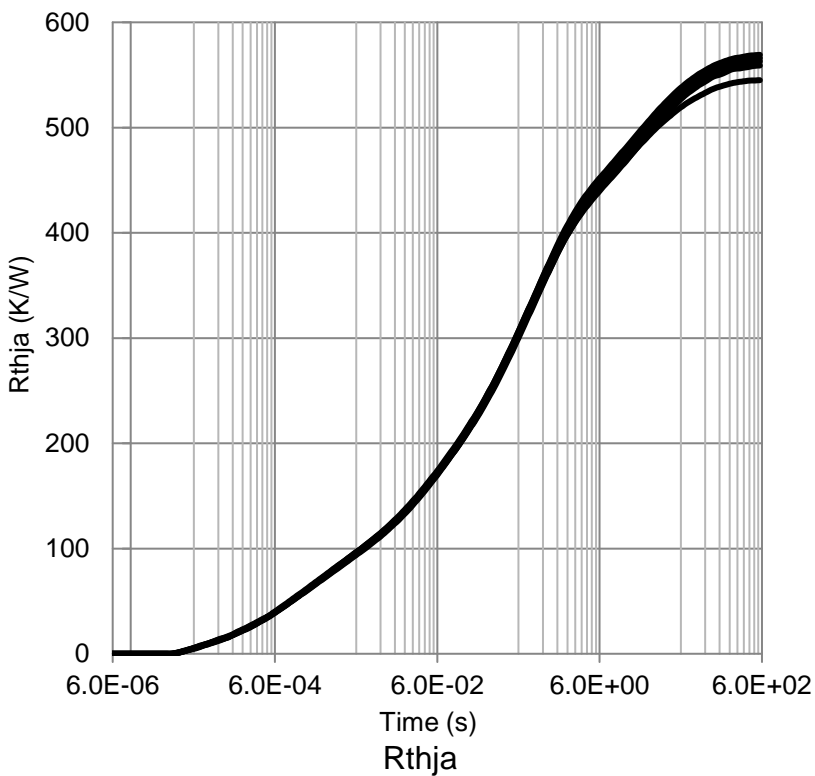
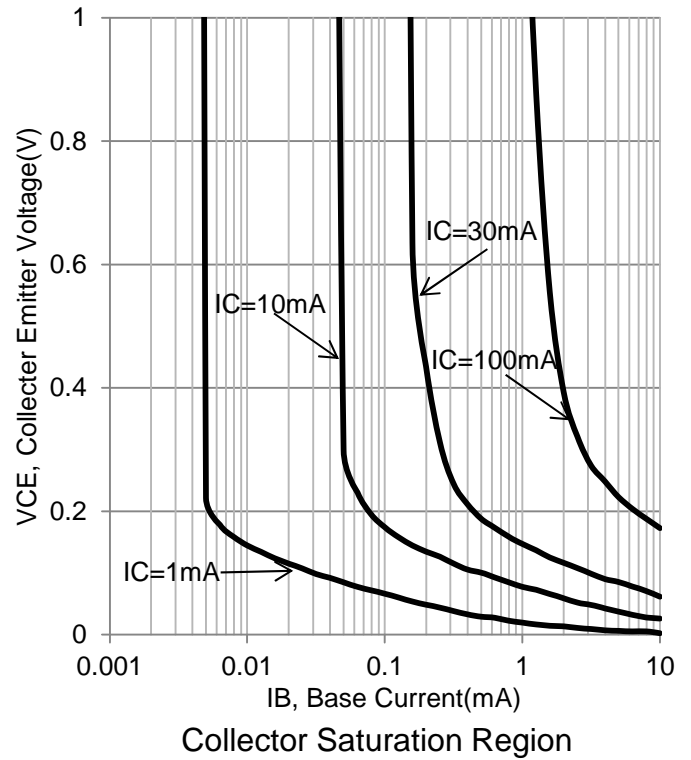
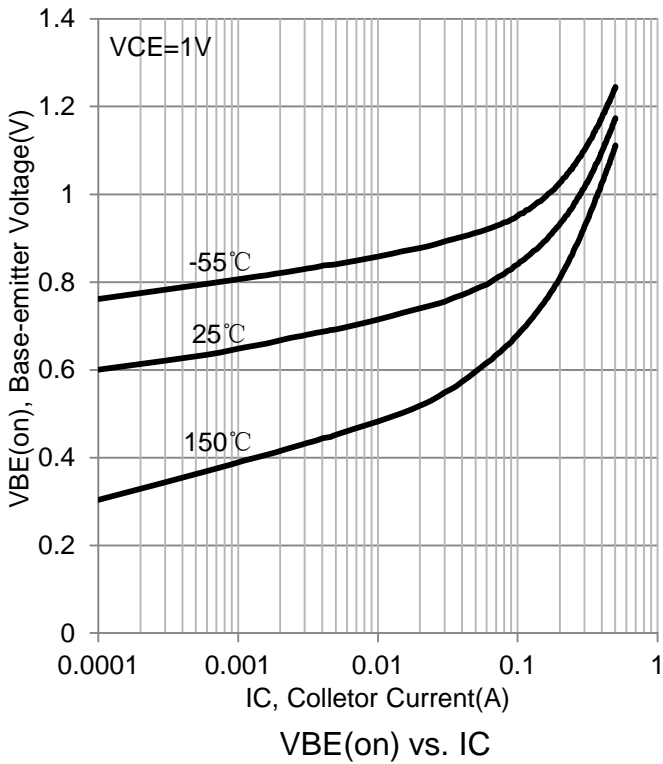
Delay Time	(VCC = 3.0 V, VBE=-0.5V, IC = 10mA, IB1 = 1.0 mA)	td	-	-	35	ns
Rise Time		tr	-	-	35	
Storage Time	(VCC = 3.0 V, IC = 10 mA, IB1 = IB2 = 1.0 mA)	ts	-	-	200	
Fall Time		tf	-	-	50	

 2.Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.

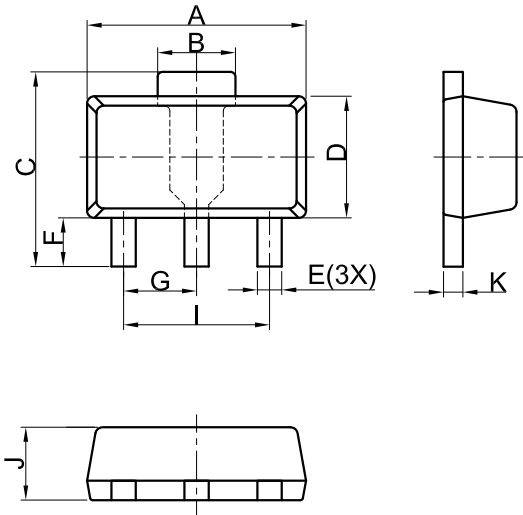
6. ELECTRICAL CHARACTERISTICS CURVES



6. ELECTRICAL CHARACTERISTICS CURVES(Con.)



7. OUTLINE AND DIMENSIONS

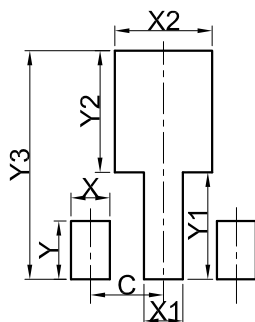


SOT89			
DIM	MIN	NOR	MAX
A	4.30	4.50	4.70
B	1.40	1.60	1.80
C	3.90	4.00	4.25
D	2.30	2.50	2.70
E	0.40	0.50	0.58
F	0.90	1.00	1.20
G	1.50 BSC		
I	3.00 BSC		
J	1.40	1.50	1.60
K	0.34	0.40	0.50
All Dimensions in mm			

GENERAL NOTES

1. Top package surface finish Ra0.4±0.2um
2. Bottom package surface finish Ra0.7±0.2um
3. Side package surface finish Ra0.4±0.2um
4. Protrusion or Gate Burrs shall not exceed 0.10mm per side.

8. SOLDERING FOOTPRINT



SOT89	
DIM	(mm)
X	0.80
Y	1.20
X1	0.80
Y1	2.20
X2	2.00
Y2	2.50
C	1.50
Y3	4.70

单击下面可查看定价，库存，交付和生命周期等信息

[>>LRC\(乐山无线电\)](#)